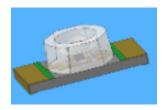


DATASHEET

Reverse Package Infrared LED EAIST3216A4



Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel
- Pb free
- The product itself will remain within RoHS compliant version.
- . Compliance with EU REACH
- . Compliance Halogen Free.(Br<900 ppm,Cl<900 ppm,Br+Cl<1500 ppm)

Descriptions

- EAIST3216A4 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.

Applications

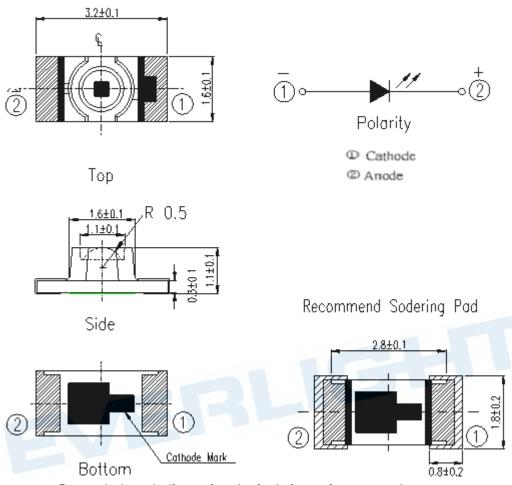
- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Device Selection Guide

LED Part No.	Chip Material	Lens Color	
EAIST3216A4	GaAlAs	Water Clear	



Package Dimensions



Suggested pad dimension is just for reference only.

Please modify the pad dimension based on individual need.

Notes: 1.All dimensions are in millimeters

- 2. Tolerances unless dimensions ±0.1 mm
- 3.Suggested pad dimension is just for reference only.

 Please modify the pad dimension based on individual need.



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units		
Continuous Forward Current	IF	65	mA		
Reverse Voltage	VR	5	V		
Operating Temperature	Topr	-25 ~ +85	$^{\circ}\!\mathbb{C}$		
Storage Temperature	Tstg	-40 ~ +85	$^{\circ}\!\mathbb{C}$		
Power Dissipation at(or below)	Pd	130	mW		
25°C Free Air Temperature					
Soldering Temperature	Tsol	Reflow Soldering : 260 °C for 10 sec.			
	1 301	Hand Soldering : 350 °C for 3 sec.			

Notes: Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

Electro-Optical Characteristics (Ta=25 ()									
Parameter	Symbol	Condition	Min.	Тур.	Max.	Units			
Radiant Intensity	le	I _F =20mA	0.5	1.5					
		I _F =100mA Pulse Width≦100μs ,Duty≦1%	ė	7.5		mW /sr			
Peak Wavelength	λр	I _F =20mA	-	940		nm			
Spectral Bandwidth	Δλ	I _F =20mA	-	45		nm			
Forward Voltage	VF	I _F =20mA		1.2	1.5	V			
		I _F =100mA Pulse Width≦100μs ,Duty≦1%		1.4	1.8				
		I _F =1A		2.6	4.0				
Reverse Current	I _R	V _R =5V			10	μA			
View Angle	201/2	I _F =20mA		160		deg			



Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

140 120 100 Forward Current (mA) 80 60 40 20 0 -25 0 20 40 100 60 80 Ambient Temperature (° C)

Fig.3 Relative Intensity vs
Forward Current

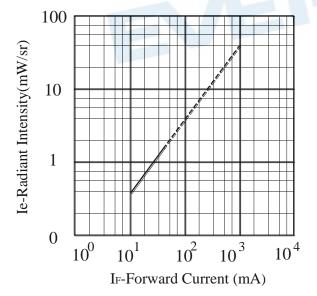
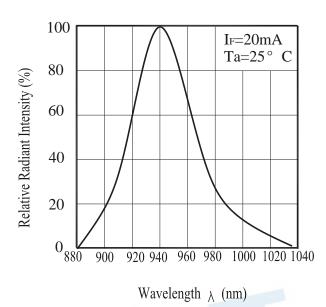
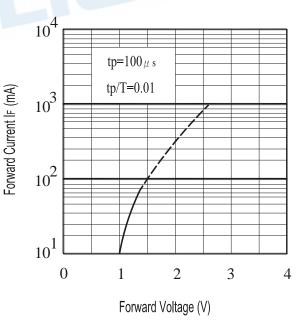


Fig.2 Spectral Distribution



4 Forward Current

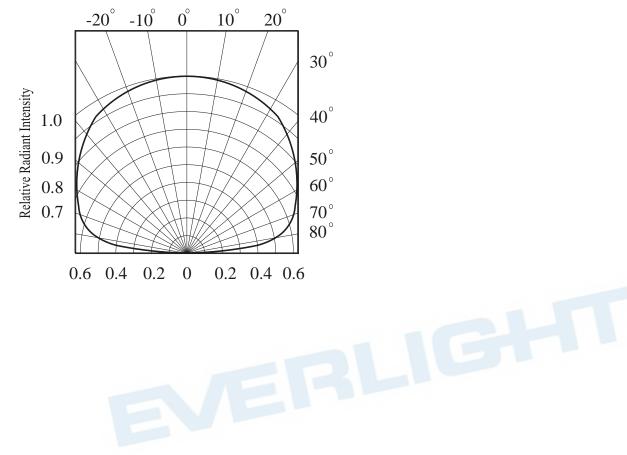
vs. Forward Voltage





Typical Electro-Optical Characteristics Curves

.Fig.5 Relative Radiant Intensity vs.
Angular Displacement





Precautions For Use

1. Over-current-proof

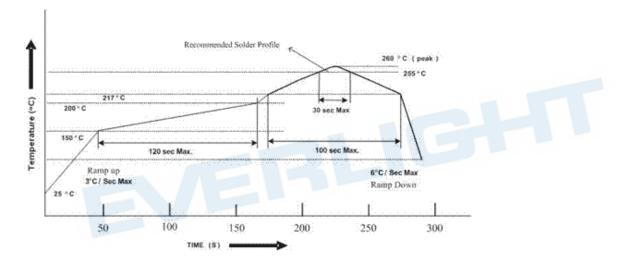
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 After opening the package: The LEDs should be kept at 30° C or less and 60%RH or less.
- 2.3 The LEDs should be used within 168 hours (7days) after opening the package .
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

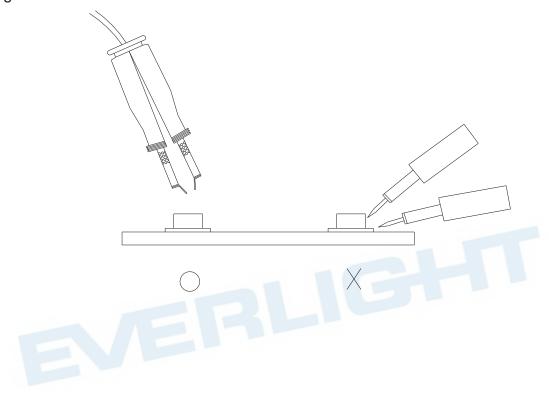


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

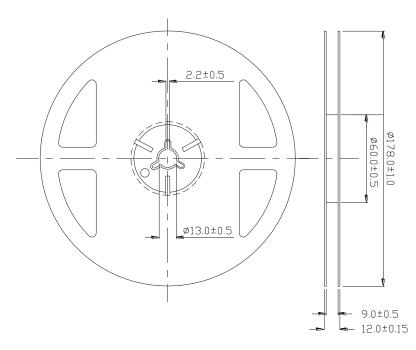
5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

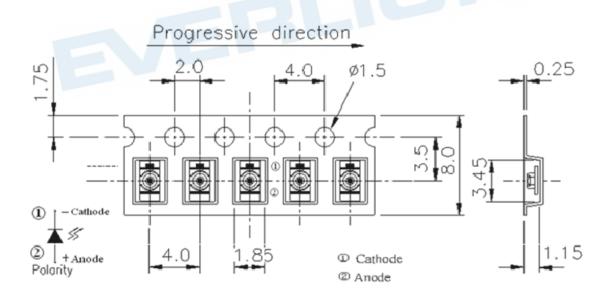




Package Dimensions



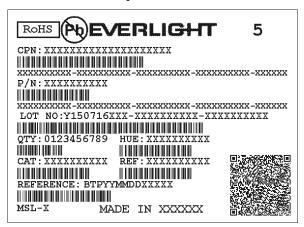
Carrier Taping Dimensions: (Quantity: 2000PCS/Reel)



Note: The tolerances unless mentioned are ±0.1mm, Unit: mm



Label Form Specification



CPN: Customer's Production Number

P/N: Production Number

LOT No: Lot Number QTY: Packing Quantity HUE: Peak Wavelength

CAT: Ranks

REF: Reference sMSL-X: MSL Level

Made In: Manufacture place

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- The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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